



ZIGMA™

PRODUCT FAMILY

Super High Performance Test Contacting Solutions

[Patent No. 8,952,714 B2]

For Analog / RF / IoT Device Testing

Contactor Lifespan

Socket Housing : ≥ 6M
Contact Pin : 300K~ 900K
Elastomer : ≥ 400K

Brings:

- Sustainable FPY
- Improved OEE
- Lower cost to Test

Advance Contact Finishing (ACF) Technology



Zigma-ACF



Others

ZIGMA™

Sustainability of SPECIFICATION & PERFORMANCE

Short Wiping Stroke (SWS) Technology



Zigma

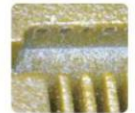


Others

No Pin Engagement with Back-Stopper



Zigma



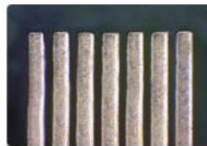
Others

Error Free in Pin Type & Elastomer Selection

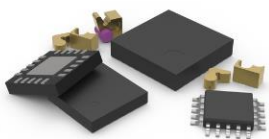


Same pin & elastomer for both PPF/NiPd & Matte Tin

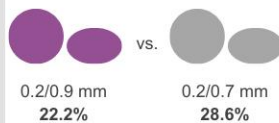
Loadboard Protected Against External Debris



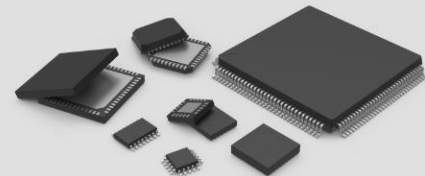
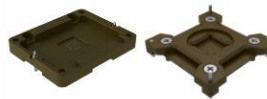
3mm x 3mm & Above Grounding Solution



Less Compression Ratio with Bigger Elastomer



XYZ Compatible with Most Socket Platforms



Solution for **Leaded & Leadless** packages*

* Package Range: SO, SOIC, TSOP, QFP, QFN, DFN

* Min. Pitch: 0.3mm

Most of the images are computer rendered. Some of it may differ from the actual part in terms of colour, size and design due to material composition, design revision and machining tolerance.

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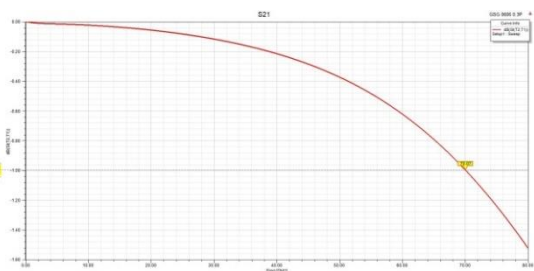
TECHNICAL SPECIFICATIONS

Electrical Specifications	Zigma2	Zigma1	Zigma.5
Self Inductance (nH)	0.42	0.29	0.19
Mutual Inductance (nH)	0.230	0.137	0.08
Ground Capacitance (pF)	0.28	0.061	0.04
Mutual Capacitance (pF)	0.150	0.056	0.02
S21 (Insertion Loss / Bandwidth)	- 1dB @ 14GHz *	- 1dB @ 40GHz *	- 1dB @ 70GHz *
S11 (Return Loss / Bandwidth)	- 20dB @ 3GHz *	- 20dB @ 16GHz *	- 20dB @ 21GHz *
S41 (Crosstalk / Bandwidth)	- 24dB @ 15GHz *	- 20dB @ 12.5GHz *	- 20dB @ 25GHz *
Contact DC Resistance (mΩ)	≤ 25.0	≤ 25.0	≤ 20.0
Current Carrying Capacity (A)	5.00	4.70	3
Current Leakage (pA) @ 10V	≤ 1.0	≤ 1.0	≤ 0.1

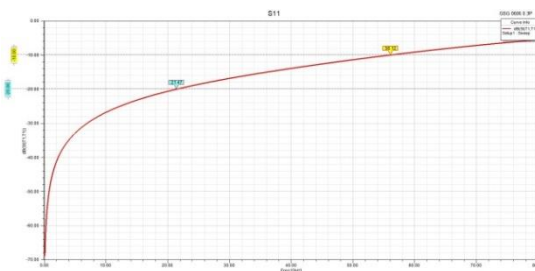
Mechanical Specifications	Zigma2	Zigma1	Zigma.5
Pin Uncompressed Height (mm)	1.60	0.925	0.50
Pin Compliance (mm)	0.20	0.175	0.10
Pin Tip Coplanarity (mm)	0.05	0.05	0.05
Pin Wiping Length (mm)	≤ 0.1	≤ 0.1	≤ 0.08
Gram Force Per Pin (g)	55 ~ 65	25 ~ 35	10 ~ 15
Number of Insertion – Housing	≥ 6M	≥ 6M	≥ 1M
Number of Insertion – Elastomer	≥ 400k	≥ 400k	≥ 100k
Number of Insertion – Pin (Matte Tin)	≥ 800k	≥ 500k	≥ 100k
Number of Insertion – Pin (NiPd)	≥ 500k	≥ 300k	≥ 100k
Operating Temperature (°c)	- 45 ~ 155	- 45 ~ 155	- 45 ~ 155
Socket Material	Torlon® 5030	Torlon® 5030	Torlon® 5030
Pin Material	BeCu - NiAu	BeCu - NiAu	BeCu - NiAu

Zigma.5 Performance^②

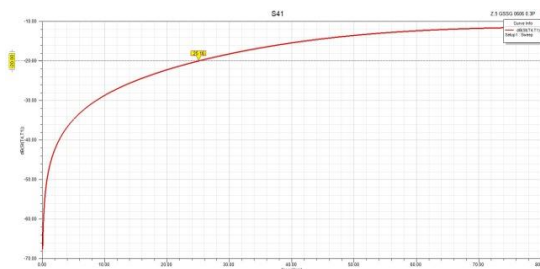
S₂₁ Insertion Loss



S₁₁ Return Loss



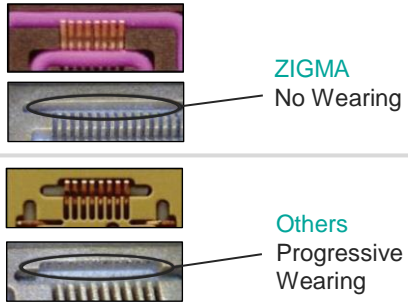
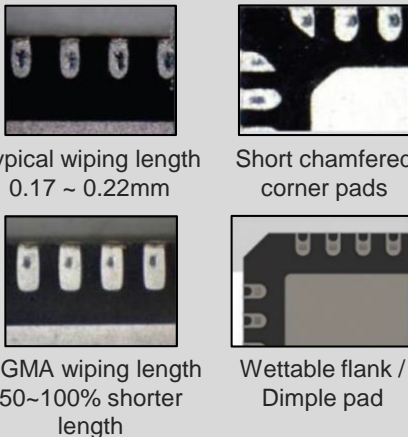

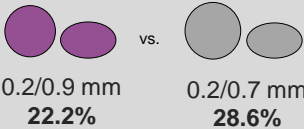


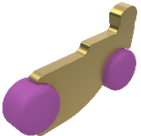
S₄₁ Crosstalk



① Specifications of this product is based on laboratory results at JF Microtechnology and field testing. The results may vary subject to variables of test environment conditions including hardware mechanism set-up, DUT conditions and other maintenance activities. Results for 0.5mm pitch configurations on matte tin finishing devices at ambient.





② Simulated Results

FEATURES & BENEFITS


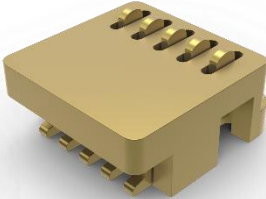

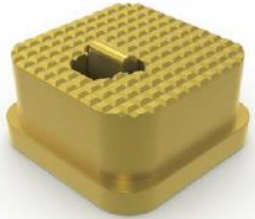
Design Feature	Illustration	Benefit
<p>No Pin Engagement with Back Stopper</p>	 <p>ZIGMA No Wearing</p> <p>Others Progressive Wearing</p>	<ul style="list-style-type: none"> • Socket lifespan: <u>≥ 6M insertions</u>
<p>Short Wiping Stroke (SWS) Technology</p>	 <p>Typical wiping length 0.17 ~ 0.22mm</p> <p>Short chamfered corner pads</p> <p>ZIGMA wiping length 50~100% shorter length</p> <p>Wettable flank / Dimple pad</p>	<ul style="list-style-type: none"> • Ideal for short pads: <u>chamfered corner</u> and <u>wettable flank / dimple pad</u> • Retains more solderability area • Less debris generation • Ideal for multiple testing insertion
<p>Advance Contact Finishing (ACF) Technology</p>	 <p>ZIGMA-ACF Others' Pin</p>	<ul style="list-style-type: none"> • Loadboard friendly • <u>Less cleaning frequency</u>
<p>Bigger Elastomer Diameter (Less Compression Ratio)</p>	 <p>0.2/0.9 mm 22.2%</p> <p>vs.</p> <p>0.2/0.7 mm 28.6%</p>	<ul style="list-style-type: none"> • <u>≥ 33% longer lifespan</u> than typical elastomer • Sustainable test performance
<p>XYZ Compatible with Most Socket</p>		<ul style="list-style-type: none"> • <u>Low or zero</u> hardware investment
<p>Debris Protection Design</p>	 <p>Debris blocked by front elastomer</p>	<ul style="list-style-type: none"> • Less loadboard cleaning frequency • Prolong loadboard lifespan
<p>Single Pin Type for Matte Tin & NiPd Finishing Devices</p> <p>Single Elastomer type for front and back slots</p>	 <p>Same pin & elastomer for both PPF/NiPd & Matte Tin</p>	<ul style="list-style-type: none"> • Error free in pin type & elastomer selection • Less inventory

ZIGMA ACCESSORIES





ZIGMA Grounding Pin Solutions

<p>Bell Contact (BC) Patented</p> 	<p>Hinged Contact Insert (HCI) Patented</p> 	<p>ZIGMA Short Pin (ZSP)</p> 	<p>ZIGMA Pin (ZP)</p> 
<p>For Package: ≥ 2x2</p>	<p>For Package: ≥ 3x3</p>	<p>For Package: ≥ 4x4</p>	<p>For Package: ≥ 5x5</p>

ZIGMA Grounding Block Solutions

<p>Ground Block</p> 	<p>Ground Block with Pins</p> 	<p>Spike Ground Block</p> 	<p>Spike Ground Block with Pins</p> 
<p>For Package: ≥ 2x2</p>	<p>For Package: ≥ 3x3</p>	<p>For Package: ≥ 4x4</p>	<p>For Package: ≥ 5x5</p>

ZIGMA Grounding Block Solutions

<p>Auto Centering Manual Actuator (ACMA)* Patent Pending</p>  <p>*Compatible with packages sizes from 2mm up to 7mm</p>	<p>Single Latch Vertical Clamp Shell</p> 	<p>Single Latch Turn Knob with Spring Loaded</p> 
	<p>Double Latch Vertical Clamp Shell</p> 	<p>Double Latch Turn Knob with Spring Loaded</p> 

Note * : The stated specifications are based on JF Microtechnology's Laboratory Test; the results may vary subjected to the test environment conditions. Information furnished by JF Microtechnology is believed to be accurate and reliable. However, no responsibility is assumed by JF Microtechnology for its use, nor for any infringements of patents or other rights of third parties that may result from its use. Specifications subject to change without notice. No license is granted by implication or otherwise under any patent or patent rights of JF Microtechnology. Trademarks and registered trademarks are the property of their respective owners.

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